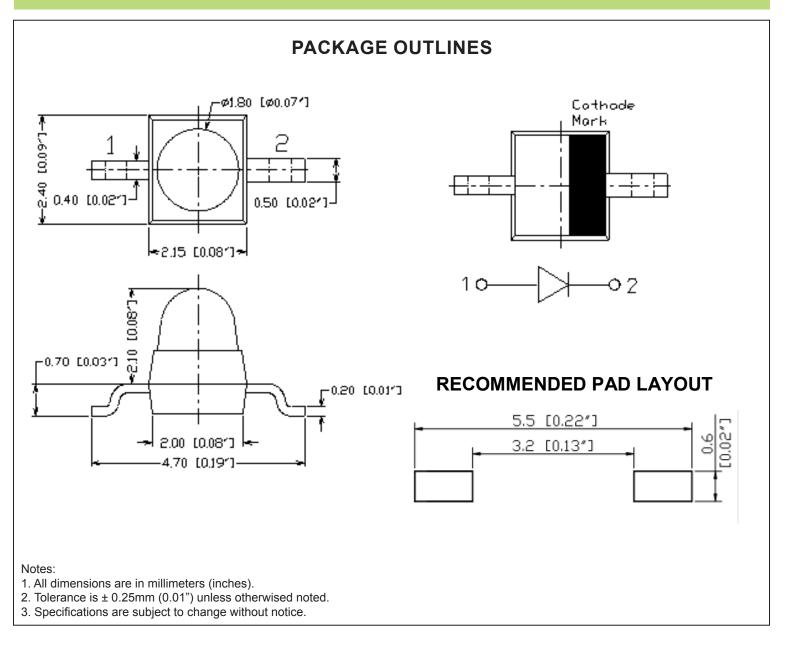


### SPECIFICATION





Part Number	Chip Material	Color of Emission Lens Type		Viewing Angle	
CSM28R2CG	InGaAIP	Red	Water Clear	20°	





## **ABSOLUTE MAXIMUM RATINGS**

### (TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	lR	10	μA	
Power Dissipation	Pd	75	mW	
Operating Temperature Range	Тор	-40~+80	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lfp	125	mA	
Soldering Temperature	Tsol	Max 260°C for 5 sec Max		

# OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

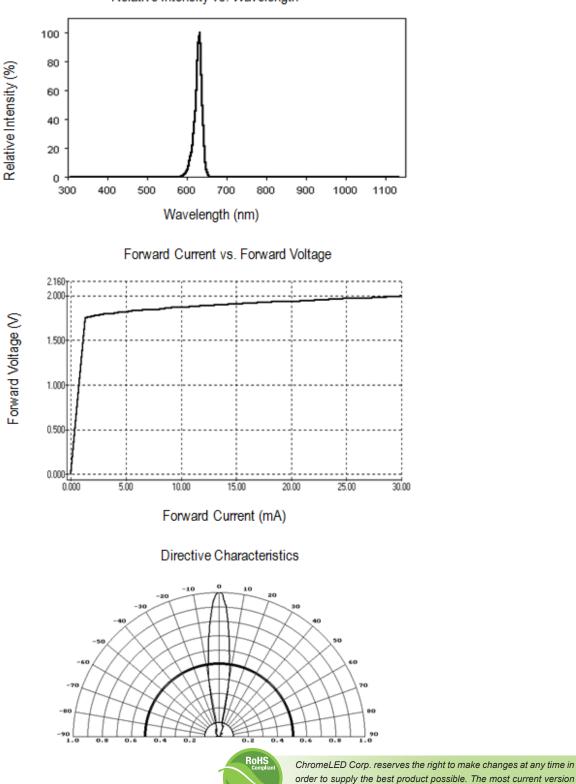
Deremeter	Symbol	Test Condition	Value			Linit
Parameter		Test Condition	Min	Тур	Max	Unit
Luminous Intensity	١v	IF = 20mA	1600	2900	-	mcd
Forward Voltage	Vf	IF = 20mA	-	2.0	2.5	V
Reverse Leakage Current	lr	VR = 5V	-	-	10	μA
Viewing Angle at 50% Iv	201/2	IF = 10mA	-	20	-	Deg
Peak Wavelength	λP	IF = 20mA	-	630	-	nm
Dominant Wavelength	λD	IF = 20mA	620	625	630	nm

\*Tolerance of viewing angle: -10 / +5 deg.





## **OPTICAL CHARACTERISTIC CURVES**



Relative Intensity vs. Wavelength

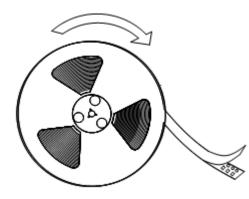
Lead Fre

of this document will always be available at: www.chromeled.com

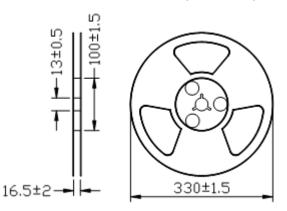


## PACKAGING SPECIFICATION

#### **Feeding Direction**

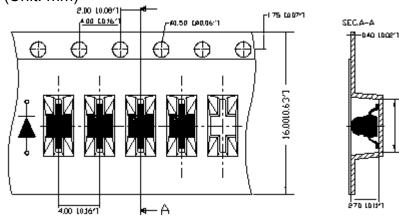


Dimensions of Reel (Unit: mm)

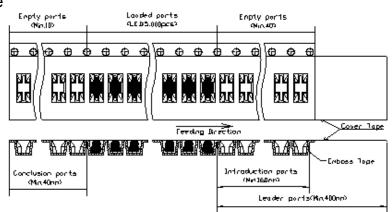


5 PCCO.PT

### Dimensions of Tape (Unit: mm)



### Arrangement of Tape



#### Notes:

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamp is two;
- 3. The cathode is oriented towards the tape sprocket hole;
- 4. 1,000 pcs/Reel

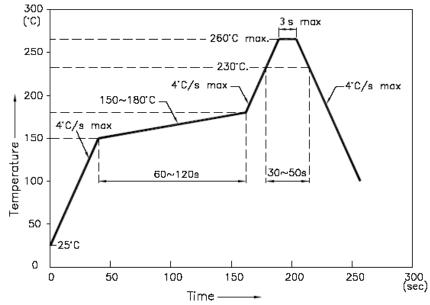




# SOLDERING CONDITIONS

### **REFLOW PROFILE**

Reflow Temp/Time



Notes:

- 1. We recommend the reflow temperature 245°C (±5°C). The maximum soldering temperature should be limited to 260°C.
- 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process should be 2 times or less.
- Soldering Iron

Basic spec is  $\leq$  5 sec when 260°C. If temperature is higher, time should be shorter (±10°C $\rightarrow$ -1sec). Power dissipation of iron should be smaller than 20W and temperature should be controllable. Surface temperature of the device should be under 230°C.

